

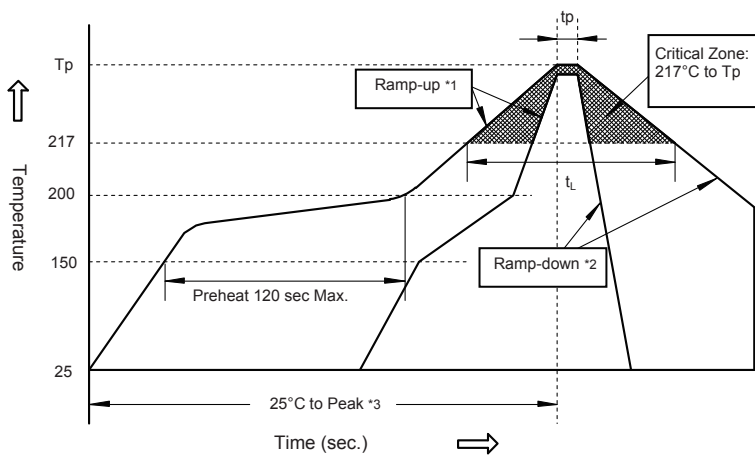
Reflow Soldering Condition for Chip Electrolytic Capacitors (SMD)

Applicable to Chip Type Aluminum Electrolytic Capacitors

■ Recommended Conditions for Reflow Soldering

- (1) A thermal condition system such as infrared radiation (IR) or hot blast should be adopted, and vapor heat transfer systems (VPS) are not recommended.
- (2) Reflow soldering should be within 2 cycles. Please make sure that the parts have enough cooling time.
- (3)
 - The time of preheating from 150°C to 200°C shall be within maximum 120 seconds;
 - The time of soldering temperature at 217°C measured on capacitors' top shall not exceed t_L (second);
 - The peak temperature on capacitors' top shall not exceed T_p (°C), and the time within 5°C of actual peak temperature shall not exceed t_p (second).

■ Classification Reflow Profile



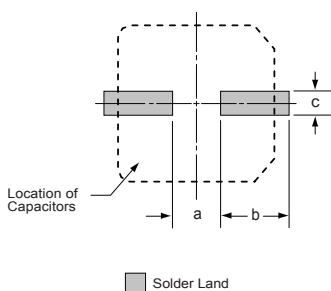
- *1. Average ramp-up rate is 3°C/second max.
 - *2. Ramp-down rate is 6°C /second max.
 - *3. Time from 25°C to peak temperature is 6 minutes max.

■ Classified at Temperature and Time

Size	Thickness (mm)	T_p (°C)	t_L (second)	t_p (second)
Ø4~Ø6.3, Ø8×6.2L	≥2.5	255	60	5
Ø8×10.5L	≥2.5	250	60	5
Ø10×10.5L/13.5L	≥2.5	245	60	5
Ø12.5, Ø16	≥2.5	240	40	5

● Please contact us if your condition is over the maximum.

■ Recommended Solder Land Size on PC Board (Unit: mm)



Size	a	b	c
Ø4	1.0	2.6	1.6
Ø5	1.4	3.0	1.6
Ø6.3	1.9	3.5	1.6
Ø8×6.2L	2.1	4.0	1.6
Ø8×10.5L	3.0	3.5	2.5
Ø10	4.0	4.0	2.5
Ø12.5	4.0	6.0	3.2
Ø16	6.0	7.0	3.5